



# Product End-of-Life Disassembly Instructions

Product Category: Notebooks and Tablet PCs

Marketing Name / Model  
[List multiple models if applicable.]

OMEN X by HP Laptop PC 17

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm M/B , Audio Board, Power Board, DB ,TP BOARD	5
Batteries	All types including standard alkaline and lithium coin or button style batteries Main Battery	1
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps 17.3"	1
Cathode Ray Tubes (CRT)		
Capacitors / condensers (Containing PCB/PCT)		
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		
External electrical cables and cords	Power Cord	1
Gas Discharge Lamps		
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	
Components and waste containing asbestos		

Components, parts and materials containing refractory ceramic fibers		
Components, parts and materials containing radioactive substances		

## 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Description #1 Screwdriver	#1,#0
Description #2	
Description #3	
Description #4	
Description #5	

## 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Dis-fasten D cover screw \*10
2. Remove D cover
3. Dis-fasten centel hook screw \*2
4. Pull out Battery cable
5. Dis-fasten battery screw \*4
6. Remove Battery
7. Dis-fasten trunk assy screw \*6
8. Remove Trunk assy
9. Dis-fasten Fan screw \*3
10. Pull out Fan cable (Left side)
11. Remove Thermal Fan
12. Dis-fasten SSD screw \*1(2)
13. Remove SSD
14. Dis-fasten Thermal module screw \*11
15. Pull out Fan cable (Right side)
16. Remove Thermal module
17. Dis-fasten Speaker screw \*2
18. Pull out Speaker cable
19. Remove Speaker -L & -R
20. Dis-fasten TP module screw \*4
21. Pull out TP cable
22. Remove TP module
23. Pull out FFC/ Wire Cable ( DB, Audio, KB, BL,PW, HDD FFC , LCD/ LED/ DC cable Antenna Cable)
24. Remove HDD assy
25. Dis-fasten PCBA screw \*7
26. Remove PCBA
27. Remove DC Cable
28. Dis-fasten Hinge Support BKT screw \*12
29. Remove LED cable & Hinge support BKT
30. Dis-fasten Hinge screw \*8
31. Remove Hinge support BKT
32. Dis-fasten Panel screw \*4
33. Pull out LCD cable
34. Remove Panel
35. Dis-fasten Hinge BKT screw \*6

36. Remove Hinge BKT L/R
37. Pull out Camera/ LED module Cable
38. Remove Antenna cable
39. Dis-fasten Hinge screw \*6
- 40.
- 41.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

### 3.21 Total part disassembly



### 3.22 Remove battery module



### 3.23 Remove service door (N/A)

### 3.24 LCD module set disassembly

- Remove Hinge support Bkt



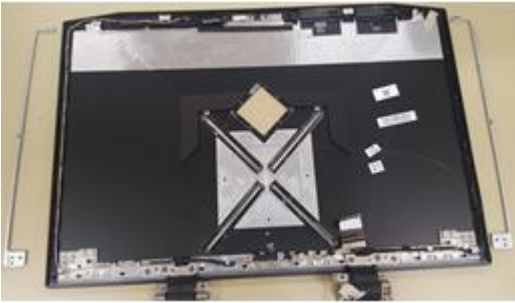
- Remove Bezel



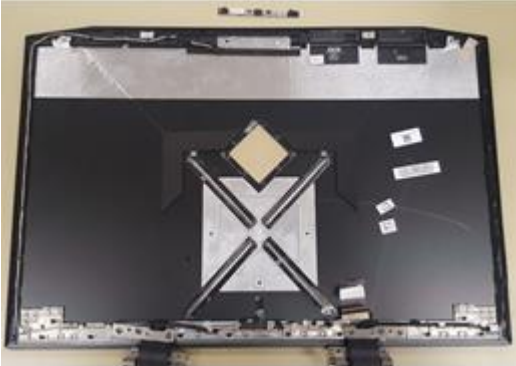
- Remove Panel



- Remove Hinge BKT L/R



- Remove Camera



- Remove Hinge (LCD /Antenna Cable)



### 3.25 Top case disassembly

- Remove center hook & Battery

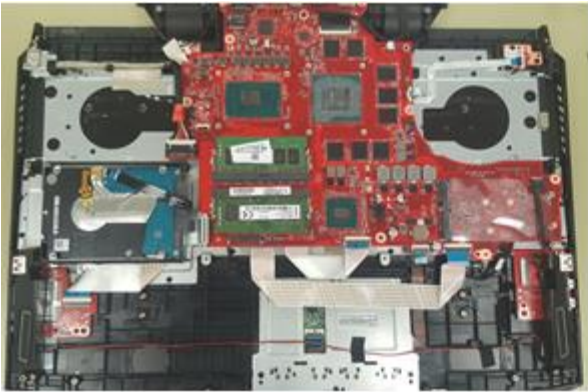


- Remove Trunk assy



- Remove Thermal Fan / SSD / Thermal module /HDD





➤ Remove Speaker



➤ Remove TP module /DC Jack / K-Lock BKT & PW /Audio Board & DB ,KB



### 3.26 Thermal module and mother board disassembly

- Remove Trunk assy

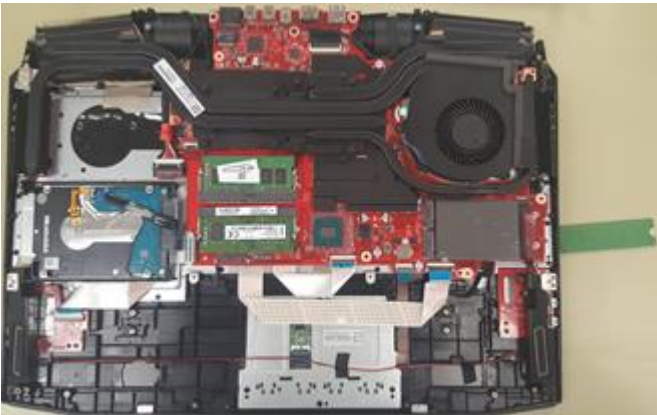




➤ Remove Thermal Fan



➤ Remove SSD

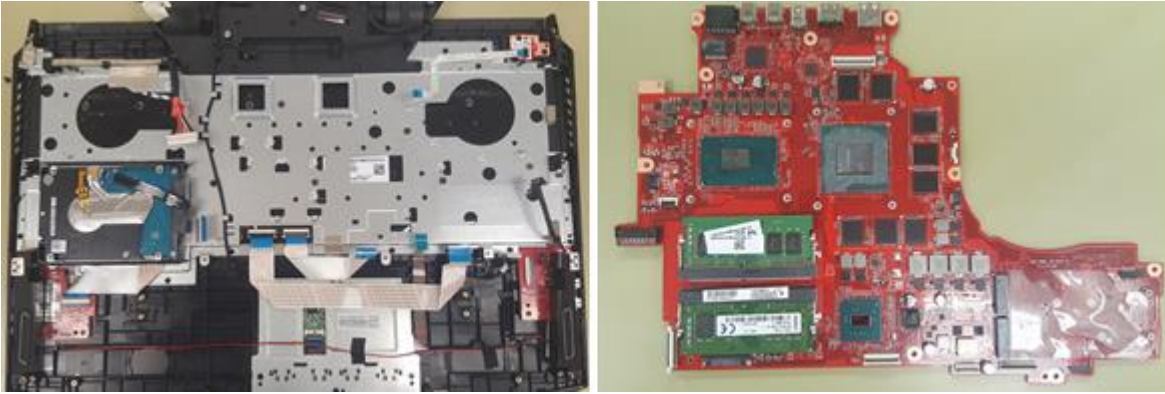


➤ Remove Thermal Module





➤ Remove PCBA



3.27 Bottom case disassembly

